Z24 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.
Z23 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
Z22 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
Z21 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANTS: [No Variations]
COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
ASSEMBLY VARIANT: [No Variations]

<table>
<thead>
<tr>
<th>PCB VIEWED FROM BOTTOM SIDE</th>
<th>BOARD #: TIDA-00199</th>
<th>REV: B</th>
<th>SVN REV: Not In VersionControl</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td></td>
<td></td>
<td>IGNORE -&gt;</td>
</tr>
<tr>
<td></td>
<td></td>
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<td>Bottom Overlay</td>
</tr>
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| PLOT NAME = Bottom Assembly Drawing | GENERATED: 11/25/2014 11:20:36 AM | TEXAS INSTRUMENTS |
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